

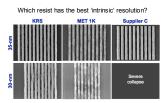
A linear systems approach to advanced EUV resist

characterization Christopher N. Anderson^{1,2}, Patrick P. Naulleau^{2,3}, Demitra Niakoula², Bruno LaFontaine⁴, Tom Wallow⁴, Elsayed Hassanein³, Robert Brainard³, Gregg Gallatin⁵, and Kim Dean⁶

1UC Berkeley, Applied Science & Technology Group, 2Center for X-ray Optics, LBNL, 3College of Nanoscale Science and Engineering, University at Albany, NY 12203, 4Advanced Micro Devices, Sunnyvale, CA 94088. 5Applied Math Solutions, LLC, 6SEMATECH, Austin, TX 787

MOTIVATION

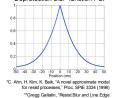
- Resist is one of the biggest challenges facing EUV development
- Problem lies in simultaneous achievement of resolution, LER and sensitivity goals
- While LER and sensitivity are easily quantified, intrinsic resolution often remains subjective



- Which metrics are best for comparing and ultimately quantifying 'intrinsic resolution'?
- Can we extract a resist blur (point-spread) function?

RESIST MODELING BASED ON THE POINT-SPREAD FUNCTION (PSF) METHOD "Deprotection blus" function PSF

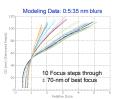
- PSF resist modeling* is fast and convenient, model easily generated
- Provides intuitive link to resist resolution limit
- Few parameters make model less susceptible to extrapolation errors



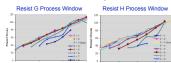
Resist process well modeled by deprotection blur function*

SENSITIVITY OF CONTACT METRIC

FOCUS - **Modeling:** generate aerial images through \pm 70-nm of best focus and observe changes in CD vs. dose.

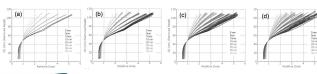


FOCUS - Experimental: observe how CD vs. dose changes through 50-nm FEM focus steps



- Excellent experimental control of focus & picking best focus from FEM; no need for full process window.
- Modeling predicts Focus-control blur-error ~ 1 nm

OPTIC ABERRATIONS: a) – d) show 0, 10, 20, and 30% rms noise level lineouts. 10 random aberration maps in each noise level

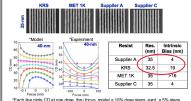


*K. Goldberg, et al. "At-Wavelength Alignment and Testing of the 0.3 NA MET Optic," J. Vac. Sci. & Technol. B *22*, 2956-2961 (2004).

- Error bars from MET optic interferometry ~ 10-20%*
- Repeating this study for the corner metric shows focus and aberration error-bars of 0.91 nm and 2.25 nm respectively**

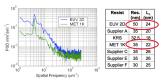
SO WHAT DOESN'T WORK?

Intrinsic bias – Find CD that remains constant through focus.
Compare model and experimental data -> the shift is the intrinsic bias



LER spatial frequency roll-off -

What is the spatial frequency cutoff of a line edge? Correlation length (Lc) inversely proportional to cutoff.

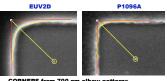


 Extracted blur not consistent with observed resolution for LER and intrinsic bias metrics

*50-nm 1:2 contacts printed in XP5435H

NEW METRICS BEING EXPLORED

50-nm 1:2 contact printing through dose - Measure printed CD through dose. Compare to modeled CD through dose for aerial images with different levels of deprotection blur.

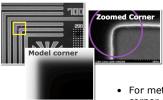


CORNERS from 700-nm elbow patterns

Modeled comer rounding at dose-to-size for 700-nm elbow corners. Deprotection blur is in nm, FWHM

dose (contacts)

CORNER ROUNDING METRIC



Add random low-order Zernike

coefficients fluctuations to MET

optic model in varying degrees

and observe changes in CD vs.

uncertainty blur-error ~ 2

**C. Anderson and P. Naulleau

"Sensitivity study of reliable, high-throughput resolution

metrics for photoresists" To be

printed J. Vac. Sci. & Technol. B Nov/Dec 2007.

•20% RMS aberration

Modeled come

 How to determine 'corner radius'? We've used three methods: 1.) least-squares circle fit, 2.) the curvature method* and 3.) the 'removed area' method.

Corner rounding of large features

Measure radius of 700-nm elbow

of deprotection blur.

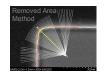
corner. Compare to modeled radius

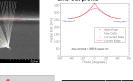
for aerial images with different levels

 We found methods 1 and 2 were subject to errors on experimental data; decided to use in-house 'removed area' method.

 For method 3 we draw radial line-outs to find corner edge vs. θ. We determine the ideal corner location from straight edges and compute the

removed area. This determines the 'effective' corner radius.



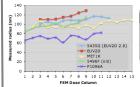


RHEM MET-1K

RHEM 5496F 35 34

RHEM XP5435G 45 42

FUJIFILM P1096A <30 20

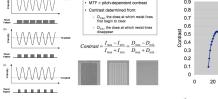


•Extracted blur consistent with observed resolution

*R. Jones, J. Byers "Theoretical Corner Rounding Analysis and Masi Writer Simulation," Proc. of SPIE 5040 (2003)

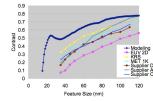
WHAT SEEMS TO HAVE WORKED IN THE PAST?

Resist-based MTF measurements - compare 'resist contrast' to modeled aerial image contrast. Blur modeled aerial image with a PSF until it's contrast vs. CD curve matches experimental data.



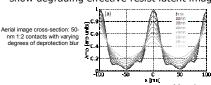
•MET1K: Modeled aerial image blurred with 21-nm HOST function matches experimental data.

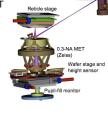




50-nm CONTACT METRIC

- Data collection All experimental images are collected at the SEMATECH Berkeley MET using 0.35 < σ < 0.55 annular illumination
- Aerial images with varying degrees of blur show degrading effective resist latent image





Reported CD is the average of the same 20 certral contacts in the 50-rm 1.2 contact array

O

Resist

RHEM EUV-2D

RHEM MET-1K

TOK EUVR-P112

TOK EUVR-P108

Resist J

Extracte

Metric can be viewed as inverse Fourier equivalent to MTF method

Resist	Res [nm]	Blur [nm]
RHEM EUV-2D	50	33.12
RHEM MET-1K	35	24.5
TOK EUVR-P1123	27	23.23
TOK EUVR-P1085	25	21.80
Resist J	20	16.49

Extracted blur consistent with observed resolution

SUMMARY

- Two new PSF-based metrics for EUV resist testing developed; both appear to give a good measure of intrinsic resolution.
- Focus and aberration sensitivity study shows ~ 2-nm error bar in extracted blur for both corner and contact methods.
- Additional testing lower-blur resist platforms needed to verify fidelity of corner and contact metrics at lower intrinsic blurs.
- Both metrics require < 10 SEM images through dose.

Acknowledgements

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